



**SPECIFICATION
FOR
LCD Module
KD022C-2B-TP**

MODULE:	KD022C-2B-TP
CUSTOMER:	

REV	DESCRIPTION	DATE
1.0	FIRST ISSUE	2014.05.29

STARTEK	INITIAL	DATE
PREPARED BY		
CHECKED BY		
APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		

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General Description

* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This model is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 2.2'TFT-LCD contains 240x320 pixels, and can display up to 262K colors.

* Features

- Low Input Voltage: 3.3V(TYP)
- Display Colors of TFT LCD: 65/262Kcolors
- Interface:3-SPI+16/18 BIT RGB interface

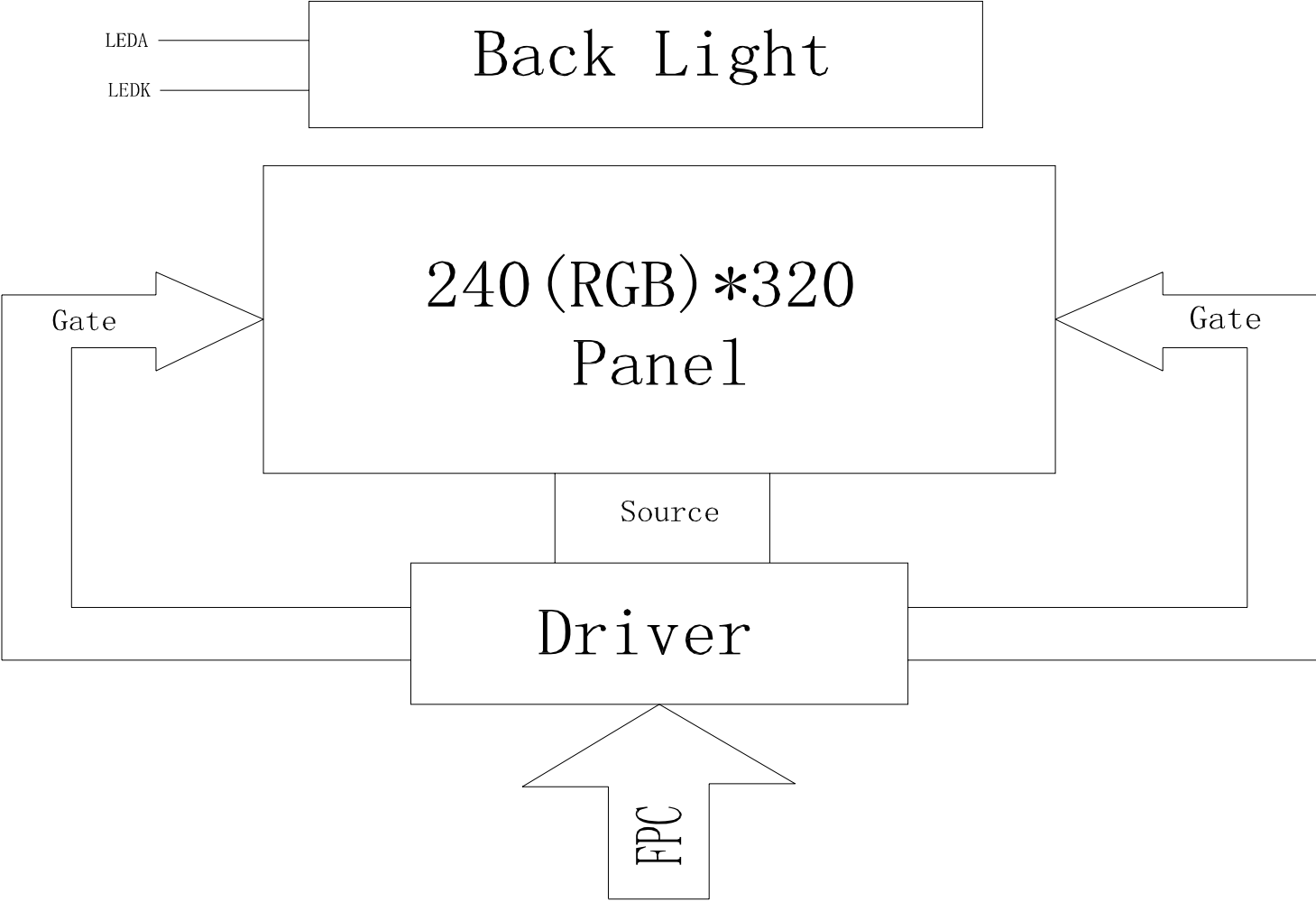
General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	33.48(H)*44.64(V) (2.2inch)	mm	-
Driver element	TFT active matrix	-	-
Display colors	262K	colors	-
Number of pixels	240(RGB)*320	dots	-
Pixel arrangement	RGB vertical stripe	-	-
Pixel pitch	0.1395(H)*0.1395(V)	mm	-
Viewing angle	12:00	o'clock	-
Controller IC	ST7789V	-	-
Display mode	Transmissive/ Normally White	-	-
Operating temperature	-20~+70	°C	-
Storage temperature	-30~+80	°C	-

* Mechanical Information

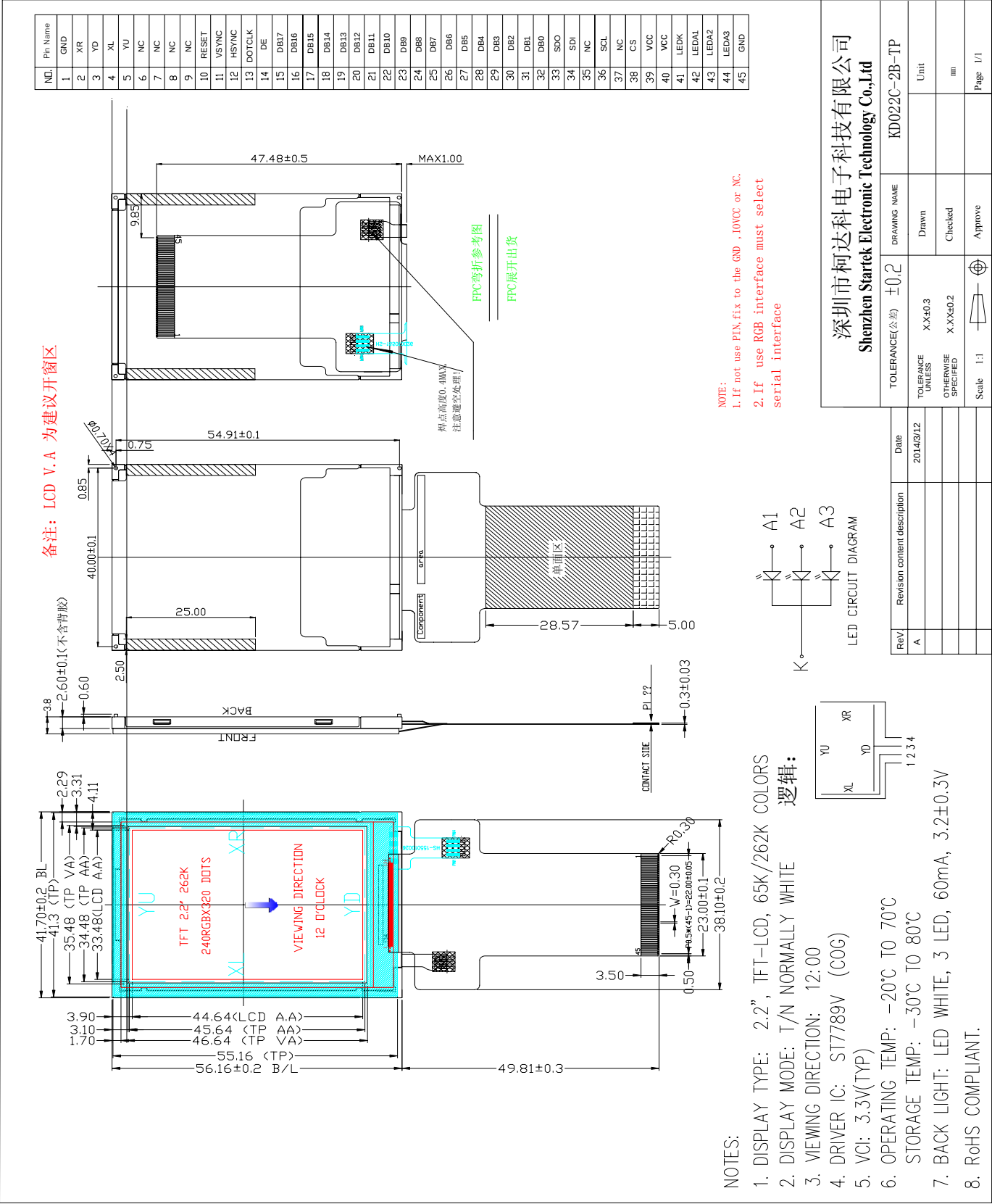
Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)		41.70		mm	-
	Vertical(V)		56.16		mm	-
	Depth(D)		3.8		mm	-
Weight			TBD		g	-



1. Block Diagram



2. Outline dimension





3. Input terminal Pin Assignment

NO.	SYMBOL	DISCRIPTION	I/O
1	GND	Ground.	P
2	XR	Touch panel Right Glass Terminal.	
3	YD	Touch panel Bottom Film Terminal	
4	XL	Touch panel LEFT Glass Terminal	
5	YU	Touch panel Top Film Terminal	
6	NC	NC	
7	NC	NC	
8	NC	NC	
9	NC	NC	
10	RESET	Setting either pin low initializes the LSI. Must be reset after power is supplied.	I
11	VSYNC	Frame synchronizing signal for DPI I/F mode. If not use, please connect to GND.	I
12	HSYNC	Frame synchronizing signal for DPI I/F mode. If not use, please connect to GND.	I
13	DOTCLK	Pixel clock signal for DPI I/F mode. If not use, please connect to VCI.	I
14	DE	A DATA ENABLE signal for DPI I/F mode. If not use, please connect to GND.	I
15-32	DB17-DB0	18-bit parallel bi-directional data bus for RGB interface mode. Fix to GND level when not in use.	I/O
33	SDO	Serial data output pin in serial bus system interface. If not used, please open this pin.	O
34	SPI-SDI/SDA	Serial data input pin or input/output pin in serial bus system interface. The data is inputted on the rising edge of the SCL signal. If not used, please connect to GND.	I
35	NC	NC	



36	SPI-SCL	DBI Type-B: Serves as a write signal and write data at the low level. DBI Type-C: it serves as SCL (Serial Clock). If not use, please connect to GND.	I
37	SPI-RS	Serves as command or parameter select. fix this pin at VCI or GND when not in use.	I
38	SPI-CS	Chip select input pin ("Low" enable). fix this pin at VCI or GND when not in use.	I
39	VCC	Supply voltage(3.3V).	P
40	VCC	Supply voltage(3.3V).	P
41	LEDK	Cathode pin of backlight	p
42	LEDA1	Anode pin of backlight	p
43	LEDA2	Anode pin of backlight	p
44	LEDA3	Anode pin of backlight	p
45	GND	Ground.	P

4. LCD Optical Characteristics

4.1 Optical specification

Item		Symbol	Condition	Min.	Typ.	Max.	Unit	Note
Transmittance (without Polarizer)		T(%)	—	—	13.5%	—	—	
Contrast Ratio		CR	$\Theta=0$	400	500	—	—	(1)(2)
Response time	Rising	T _R	Normal viewing angle — —	—	2	4	msec	(1)(3)
	Falling	T _F		—	6	12		
Color gamut		S(%)			60		%	
Color chromaticity (CIE1931)	White	W _x		0.283	0.303	0.323		(1)(4) CF glass
		W _y		0.305	0.325	0.345		
	Red	R _x		0.606	0.626	0.646		
		R _y		0.314	0.334	0.354		
	Green	G _x		0.257	0.277	0.297		
		G _y		0.529	0.549	0.569		
	Blue	B _x		0.122	0.142	0.162		
		B _y		0.102	0.122	0.142		
Viewing angle	Hor.	Θ_L	CR>10	60	70	—		Viewing Angle base on using EWV Polarizer , Reference Only
		Θ_R		60	70	—		
	Ver.	Θ_U		60	70	—		
		Θ_D		45	55	—		
Optima View Direction		12 O'clock						(5)

4.2 Measuring Condition

- Measuring surrounding : dark room
- Ambient temperature : 25±2oC
- 15min. warm-up time

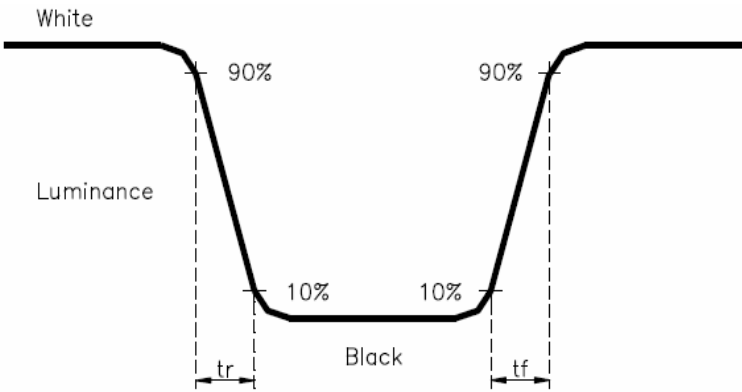
4.3 Measuring Equipment

FPM520 of Westar Display technologies, INC., which utilized SR-3 for Chromaticity and BM-5A for other optical characteristics.

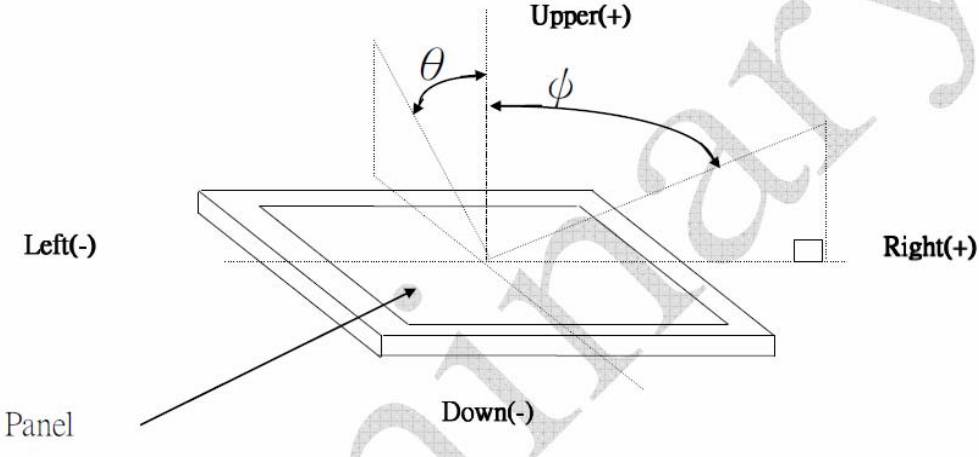
Note 3. Definition of Contrast Ratio :

CR = White Luminance (ON) / Black Luminance (OFF)

Note 4. Definition of response time : The response time is defined as the time interval between the 10% and 90% amplitudes.



Note 5. Definition of view angle(θ , ψ) :





5. Electrical Characteristics

5.1 Absolute Maximum Rating (Ta=25 VSS=0V)

Characteristics	Symbol	Min.	Max.	Unit
Digital Supply Voltage	VDD	-0.3	4.6	V
Digital interface supply Voltage	VDDIO	-0.3	4.6	V
Operating temperature	T _{OP}	-20	+70	°C
Storage temperature	T _{ST}	-30	+80	°C

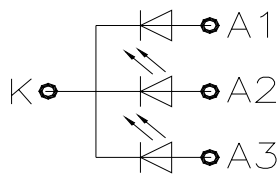
5.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	VDD	2.6	3.3	4.2	V	
Digital interface supply Voltage	VDDIO	1.65	3.3	4.2	V	
Normal mode Current consumption	IDD	--	8	--	mA	
Level input voltage	V _{IH}	0.7V _{DDIO}		VDDIO	V	
	V _{IL}	GND		0.3V _{DDIO}	V	
Level output voltage	V _{OH}	0.8VDDIO		VDDIO	V	
	V _{OL}	GND		0.2VDDIO	V	

5.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 3 chips White LED

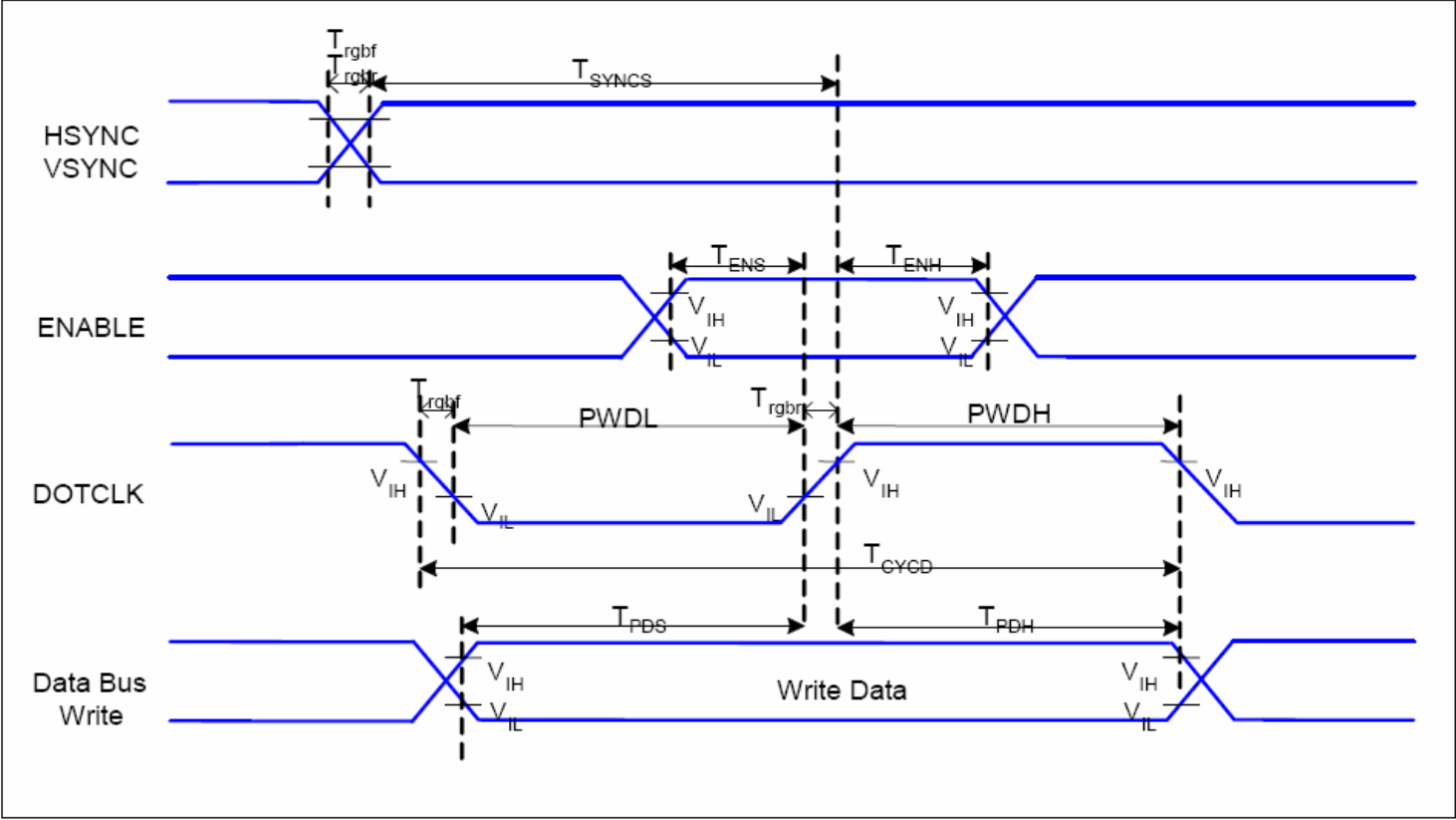
Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	45	60	--	mA	
Forward Voltage	V_F	--	3.2	--	V	
LCM Luminance	L_V	200	--	--	cd/m2	
Uniformity	AV_g	80	--	--	%	



BLU CIRCUIT DIAGRAM

6. AC Characteristic

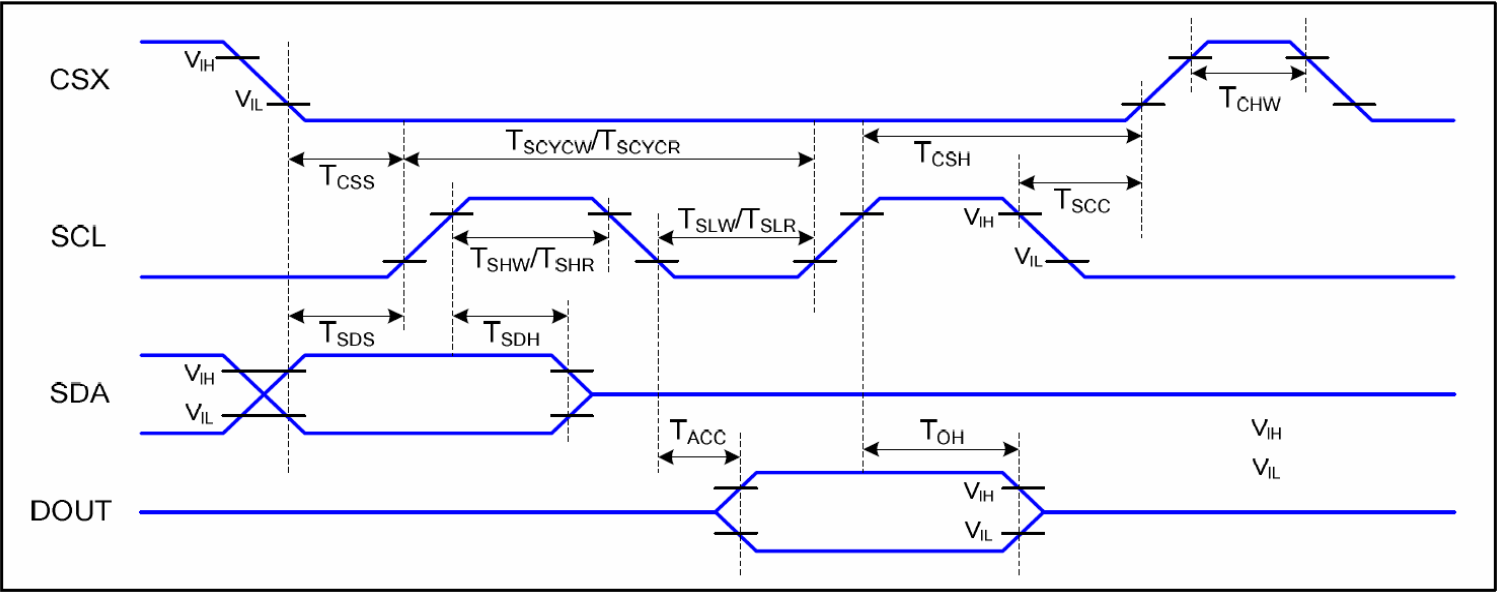
6.1 RGB Interface Characteristics:



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 ~ 70 °C

Signal	Symbol	Parameter	MIN	MAX	Unit	Description
HSYNC, VSYNC	T_{SYNCS}	VSYNC, HSYNC Setup Time	30	-	ns	
ENABLE	T_{ENS}	Enable Setup Time	25	-	ns	
	T_{ENH}	Enable Hold Time	25	-	ns	
DOTCLK	PWDH	DOTCLK High-level Pulse Width	60	-	ns	
	PWDL	DOTCLK Low-level Pulse Width	60	-	ns	
	T_{CYCD}	DOTCLK Cycle Time	120	-	ns	
	Trghr, Trghf	DOTCLK Rise/Fall time	-	20	ns	
DB	T_{PDS}	PD Data Setup Time	50	-	ns	
	T_{PDH}	PD Data Hold Time	50	-	ns	

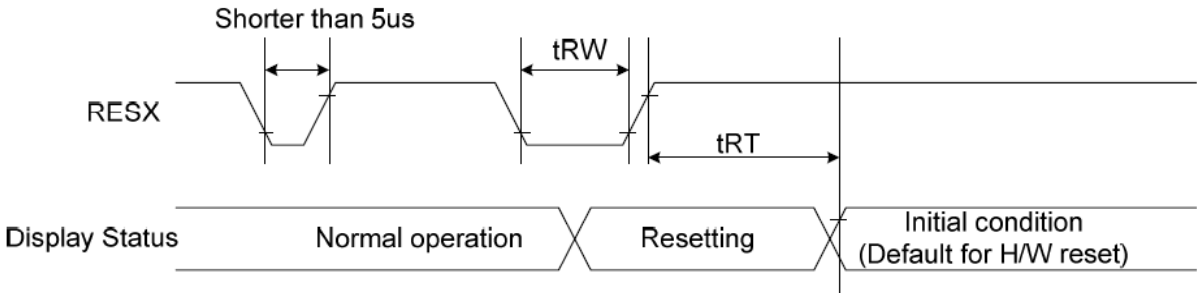
6.2 Serial Interface Characteristics (3-line serial):



VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=-30 to 70 ℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
CSX	T_{CSS}	Chip select setup time (write)	15		ns	
	T_{CSH}	Chip select hold time (write)	15		ns	
	T_{CSS}	Chip select setup time (read)	60		ns	
	T_{SCC}	Chip select hold time (read)	65		ns	
	T_{CHW}	Chip select "H" pulse width	40		ns	
SCL	T_{SCYCW}	Serial clock cycle (Write)	66		ns	
	T_{SHW}	SCL "H" pulse width (Write)	15		ns	
	T_{SLW}	SCL "L" pulse width (Write)	15		ns	
	T_{SCYCR}	Serial clock cycle (Read)	150		ns	
	T_{SHR}	SCL "H" pulse width (Read)	60		ns	
	T_{SLR}	SCL "L" pulse width (Read)	60		ns	
SDA (DIN)	T_{SDS}	Data setup time	10		ns	
	T_{SDH}	Data hold time	10		ns	
DOUT	T_{ACC}	Access time	10	50	ns	For maximum CL=30pF
	T_{OH}	Output disable time	15	50	ns	For minimum CL=8pF

6.3 Reset Timing Characteristics



Signal	Symbol	Parameter	Min	Max	Unit
RESX	tRW	Reset pulse duration	10		uS
	tRT	Reset cancel		5 (note 1,5)	mS
				120 (note 1,6,7)	mS

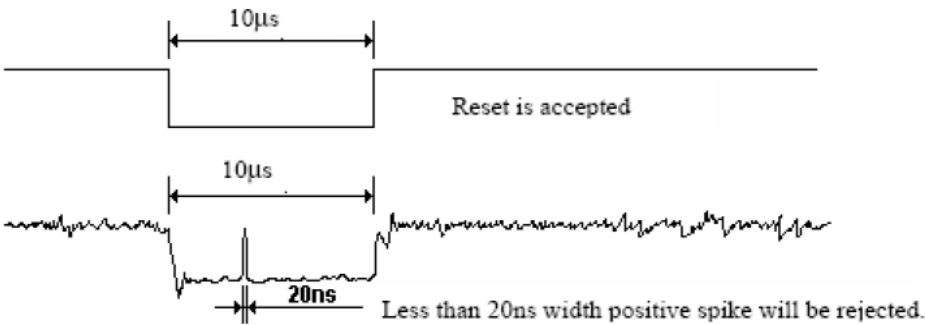
Note 1: The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from EEPROM to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.

Note 2: Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

Note 3: During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In -mode.) and then return to Default condition for Hardware Reset.

Note 4: Spike Rejection also applies during a valid reset pulse as shown below:



Note 5: When Reset applied during Sleep In Mode.

Note 6: When Reset applied during Sleep Out Mode.

Note7: It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

7. LCD Module Out-Going Quality Level

7.1 VISUAL & FUNCTION INSPECTION STANDARD

7.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

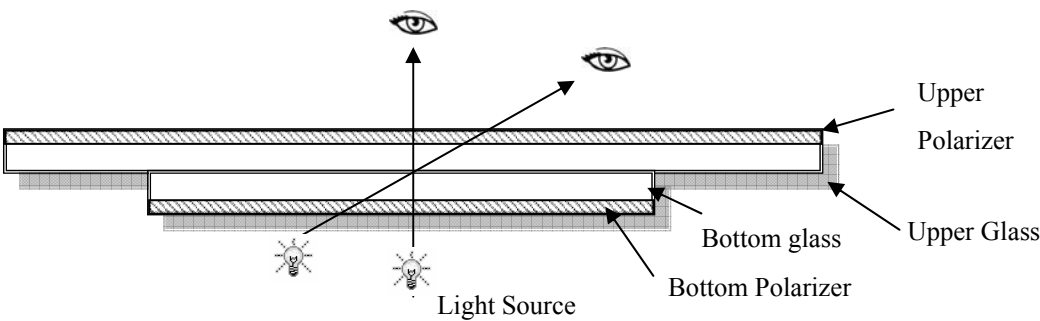
Temperature : 25±5℃

Humidity : 65%±10%RH

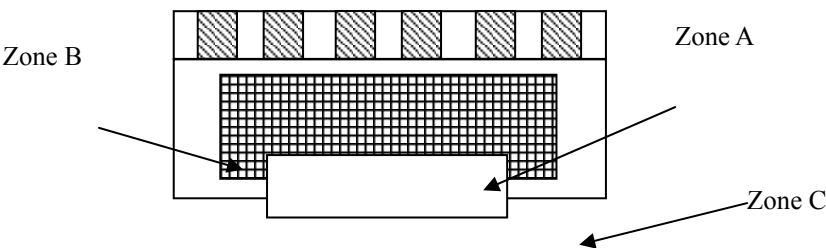
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance:30-50cm



7.1.2 Definition



Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)

Note:

As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer.

7.1.3 Sampling Plan

According to GB/T 2828-2003 ; , normal inspection, Class II

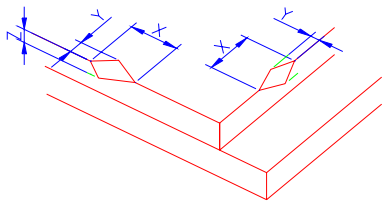
AQL:

Major defect	Minor defect
0.65	1.5

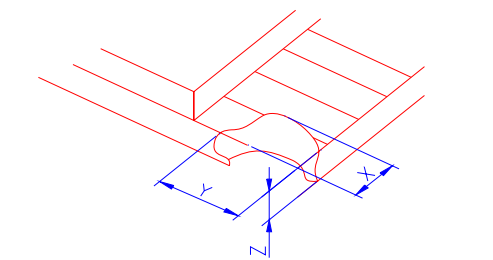
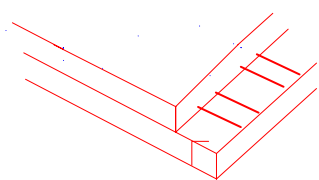
LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Soldering appearance	Good soldering , Peeling off is not allowed.	
6	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

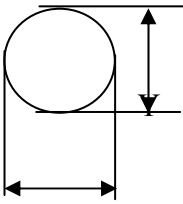
7.1.4 Criteria (Visual)

Number	Items	Criteria(mm)						
1.0 LCD Crack/Broken		 <table> <tr> <th>X</th><th>Y</th><th>Z</th></tr> <tr> <td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr> </table>	X	Y	Z	≤3.0mm	<Inner border line of the seal	≤T
X	Y	Z						
≤3.0mm	<Inner border line of the seal	≤T						
NOTE: X: Length Y: Width Z: Height L: Length of ITO,	(1) The edge of LCD broken							



T: Height of LCD	(2)LCD corner broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	≤L	≤T
	X	Y	Z					
≤3.0mm	≤L	≤T						
(3) LCD crack	 Crack Not allowed							



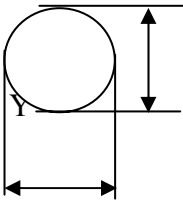
Number	Items	Criteria (mm)																							
2.0	Spot defect  X Φ=(X+Y)/2	① light dot （LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain）																							
		<table><tr><th rowspan="2">Zone Size (mm)</th><th colspan="3">Acceptable Qty</th></tr><tr><th>A</th><th>B</th><th>C</th></tr><tr><td>Φ≤0.10</td><td colspan="3">Ignore</td></tr><tr><td>0.10<Φ≤0.15</td><td colspan="3">3(distance ≥ 10mm)</td></tr><tr><td>0.15<Φ≤0.2</td><td colspan="3">1</td></tr><tr><td>0.2<Φ</td><td colspan="3">0</td></tr></table>	Zone Size (mm)	Acceptable Qty			A	B	C	Φ≤0.10	Ignore			0.10<Φ≤0.15	3(distance ≥ 10mm)			0.15<Φ≤0.2	1			0.2<Φ	0		
		Zone Size (mm)		Acceptable Qty																					
			A	B	C																				
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		0.10<Φ≤0.15	3(distance ≥ 10mm)																						
		0.15<Φ≤0.2	1																						
		0.2<Φ	0																						
		②Dim spot （LCD/TP/Polarizer dim dot, light leakage、 dark spot）																							
		<table><tr><th rowspan="2">Zone Size (mm)</th><th colspan="3">Acceptable Qty</th></tr><tr><th>A</th><th>B</th><th>C</th></tr><tr><td>Φ≤0.1</td><td colspan="3">Ignore</td></tr><tr><td>0.1<Φ≤0.2</td><td colspan="3">2(distance ≥ 10mm)</td></tr><tr><td>0.2<Φ≤0.3</td><td colspan="3">1</td></tr><tr><td>Φ > 0.3</td><td colspan="3">0</td></tr></table>	Zone Size (mm)	Acceptable Qty			A	B	C	Φ≤0.1	Ignore			0.1<Φ≤0.2	2(distance ≥ 10mm)			0.2<Φ≤0.3	1			Φ > 0.3	0		
Zone Size (mm)	Acceptable Qty																								
	A	B	C																						
Φ≤0.1	Ignore																								
0.1<Φ≤0.2	2(distance ≥ 10mm)																								
0.2<Φ≤0.3	1																								
Φ > 0.3	0																								
③ Polarizer accidented spot																									
<table><tr><th rowspan="2">Zone Size (mm)</th><th colspan="3">Acceptable Qty</th></tr><tr><th>A</th><th>B</th><th>C</th></tr><tr><td>Φ≤0.2</td><td colspan="3">Ignore</td></tr><tr><td>0.2<Φ≤0.5</td><td colspan="3">2(distance ≥ 10mm)</td></tr><tr><td>Φ>0.5</td><td colspan="3">0</td></tr></table>	Zone Size (mm)	Acceptable Qty			A	B	C	Φ≤0.2	Ignore			0.2<Φ≤0.5	2(distance ≥ 10mm)			Φ>0.5	0								
Zone Size (mm)		Acceptable Qty																							
	A	B	C																						
Φ≤0.2	Ignore																								
0.2<Φ≤0.5	2(distance ≥ 10mm)																								
Φ>0.5	0																								



Line defect (LCD/TP /Polarizer black/white line, scratch, stain)					
	Width(mm)	Length(mm)	Acceptable Qty		
			A	B	C
	$\Phi \leq 0.03$	Ignore	Ignore		Ignore
	$0.03 < W \leq 0.05$	$L \leq 3.0$	$N \leq 2$		
	$0.05 < W \leq 0.08$	$L \leq 2.0$	$N \leq 2$		
$0.08 < W$	Define as spot defect				
Items	Criteria (mm)				



Spot defect



X

$$\Phi = (X + Y) / 2$$

① light dot (LCD/TP/Polarizer black/white spot, light dot, pinhole, dent, stain)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.10$	Ignore		Ignore
$0.10 < \Phi \leq 0.15$	3(distance $\geq 10\text{mm}$)		
$0.15 < \Phi \leq 0.2$	1		
$0.2 < \Phi$	0		

② Dim spot (LCD/TP/Polarizer dim dot, light leakage, dark spot)

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.1$	Ignore		Ignore
$0.1 < \Phi \leq 0.2$	2(distance $\geq 10\text{mm}$)		
$0.2 < \Phi \leq 0.3$	1		
$\Phi > 0.3$	0		

③ Polarizer accidented spot

Zone Size (mm)	Acceptable Qty		
	A	B	C
$\Phi \leq 0.2$	Ignore		Ignore
$0.2 < \Phi \leq 0.5$	2(distance $\geq 10\text{mm}$)		
$\Phi > 0.5$	0		

Line defect

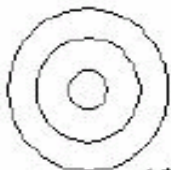
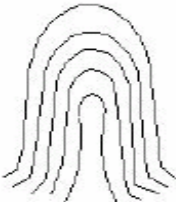
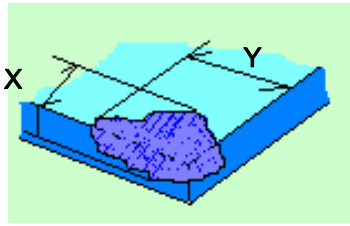
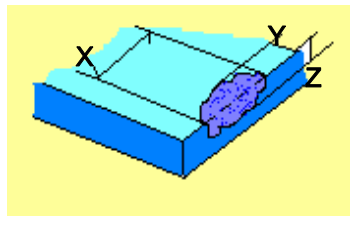
(LCD/TP
/Polarizer
black/white
line, scratch,
stain)

Width(mm)	Length(mm)	Acceptable Qty		
		A	B	C
$\Phi \leq 0.03$	Ignore	Ignore		Ignore
$0.03 < W \leq 0.05$	$L \leq 3.0$	$N \leq 2$		
$0.05 < W \leq 0.08$	$L \leq 2.0$	$N \leq 2$		
$0.08 < W$	Define as spot defect			



	Polarizer Bubble	<table><tr><th rowspan="2">Zone Size (mm)</th><th colspan="3">Acceptable Qty</th></tr><tr><th>A</th><th>B</th><th>C</th></tr><tr><td>$\Phi\leq0.2$</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>$0.2<\Phi\leq0.4$</td><td colspan="2">2(distance $\geq 10\text{mm}$)</td></tr><tr><td>$0.4<\Phi\leq0.6$</td><td colspan="2">1</td></tr><tr><td>$0.6<\Phi$</td><td colspan="2">0</td></tr></table>				Zone Size (mm)	Acceptable Qty			A	B	C	$\Phi\leq0.2$	Ignore		Ignore	$0.2<\Phi\leq0.4$	2(distance $\geq 10\text{mm}$)		$0.4<\Phi\leq0.6$	1		$0.6<\Phi$	0	
Zone Size (mm)	Acceptable Qty																								
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$0.4<\Phi\leq0.6$	1																								
$0.6<\Phi$	0																								
	SMT	According to IPC-A-610C class II standard . Function defect and missing part are major defect ,the others are minor defect.																							

		TP bubble/ accidented spot	<table><tr><th rowspan="2">Size $\Phi(\text{mm})$</th><th colspan="3">Acceptable Qty</th></tr><tr><th>A</th><th>B</th><th>C</th></tr><tr><td>$\Phi\leq0.1$</td><td colspan="2">Ignore</td><td rowspan="4">Ignore</td></tr><tr><td>$0.1<\Phi\leq0.2$</td><td colspan="2">2 (distance $\geq 10\text{mm}$)</td></tr><tr><td>$0.2<\Phi\leq0.3$</td><td colspan="2">1</td></tr><tr><td>$0.3<\Phi$</td><td colspan="2">0</td></tr></table>			Size $\Phi(\text{mm})$	Acceptable Qty			A	B	C	$\Phi\leq0.1$	Ignore		Ignore	$0.1<\Phi\leq0.2$	2 (distance $\geq 10\text{mm}$)		$0.2<\Phi\leq0.3$	1		$0.3<\Phi$	0		
Size $\Phi(\text{mm})$	Acceptable Qty																									
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$0.3<\Phi$	0																									
	Assembly deflection	beyond the edge of backlight $\leq0.15\text{mm}$																								

5.0	TP Related			 1 规律性						
		Newton Ring	Newton Ring area>1/3 TP area NG Newton Ring area≤1/3 TP area OK	 2 非规律性						
				 似牛顿环						
		TP corner broken X : length Y : width Z : height	<table border="1"><thead><tr><th>X</th><th>Y</th><th>Z</th></tr></thead><tbody><tr><td>X≤3.0mm</td><td>Y≤3.0mm</td><td>Z<LCD thickness</td></tr></tbody></table> * Circuitry broken is not allowed.	X	Y	Z	X≤3.0mm	Y≤3.0mm	Z<LCD thickness	
X	Y	Z								
X≤3.0mm	Y≤3.0mm	Z<LCD thickness								
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X	Y	Z								
X≤6.0mm	Y≤2.0mm	Z<LCD thickness								



Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed



8. Reliability Test Result

8.1 Condition

Item	Condition	Sample Size	Test Result	Note
Low Temperature Operating Life test	-20℃, 96HR	3ea	pass	-
Thermal Humidity Operating Life test	60℃, 90%RH, 96HR	3ea	pass	-
Temperature Cycle ON/OFF test	-20℃ ↔ 70℃, ON/OFF, 20CYC	3ea	pass	(1)
High Temperature Storage test	80℃, 96HR	3ea	pass	-
Low Temperature Storage test	- 30℃, 96HR	3ea	pass	-
Thermal Shock Resistance	The sample should be allowed to stand the following 5 cycles of operation: TSTL for 30 minutes -> normal temperature for 5 minutes -> TSTH for 30 minutes -> normal temperature for 5 minutes, as one cycle, then taking it out and drying it at normal temperature, and allowing it stand for 24 hours	3ea	pass	
Box Drop Test	1 Corner 3 Edges 6 faces, 66cm(MEDIUM BOX)	1box	pass	-

Note (1) ON Time over 10 seconds, OFF Time under 10 seconds

9. Cautions and Handling Precautions

9.1 Handling and Operating the Module

(1) When the module is assembled, it should be attached to the system firmly.

Do not warp or twist the module during assembly work.

(2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.

(3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.

(4) Do not allow drops of water or chemicals to remain on the display surface.

If you have the droplets for a long time, staining and discoloration may occur.

(5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.

(6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.

Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.

(7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.

(8) Protect the module from static; it may cause damage to the CMOS ICs.

(9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.

(10) Do not disassemble the module.

(11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.

(12) Pins of I/F connector shall not be touched directly with bare hands.

(13) Do not connect, disconnect the module in the “Power ON” condition.

(14) Power supply should always be turned on/off by the item 6.1 Power On Sequence & 6.2 Power Off Sequence

9.2 Storage and Transportation.

(1) Do not leave the panel in high temperature, and high humidity for a long time.

It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%

(2) Do not store the TFT-LCD module in direct sunlight.

(3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.

(4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.

In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.

(5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.

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10.Packing

---TBD---

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